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24	AO	R. Tummala et al., MICROELECTRONICS PACKAGING HANDBOOK, PART II, SEMICONDUCTOR PACKAGING, (Second Edition, 1997) pp. 78-81, 165-169 and 305-311.								
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.										